# 2057737-1 ✓ ACTIVE

### **IMPACT**

TE Internal #: 2057737-1

96 Position, Mating Alignment, Guide Pin Mating Alignment Type, 6 Row, 16 Column, PCB Mount Header, Vertical, IMPACT, High

Speed Backplane Connectors

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors











Number of Positions: 96

Row-to-Row Spacing: 1.35 mm [ .053 in ]

Mating Alignment: With

Mating Alignment Type: Guide Pin

Number of Rows: 6

## **Features**

## **Product Type Features**

Connector System Connector & Contact Terminates To Printed Circuit Board PCB Connector Assembly Type PCB Mount Header Shroud Style Partially Shrouded  Configuration Features  Number of Ground Positions 32 Number of Pairs 32 Stackable No Number of Signal Positions Number of Positions 96 Number of Rows Number of Columns PCB Mount Orientation Vertical	Signal Arrangement	Differential
PCB Connector Assembly Type PCB Mount Header  Shroud Style Partially Shrouded  Configuration Features  Number of Ground Positions 32  Number of Pairs 32  Stackable No  Number of Signal Positions 64  Number of Positions 96  Number of Rows 6  Number of Columns 16	Connector System	Board-to-Board
Shroud Style Partially Shrouded  Configuration Features  Number of Ground Positions 32  Number of Pairs 32  Stackable No  Number of Signal Positions 64  Number of Positions 96  Number of Rows 6  Number of Columns 16	Connector & Contact Terminates To	Printed Circuit Board
Configuration FeaturesNumber of Ground Positions32Number of Pairs32StackableNoNumber of Signal Positions64Number of Positions96Number of Rows6Number of Columns16	PCB Connector Assembly Type	PCB Mount Header
Number of Ground Positions32Number of Pairs32StackableNoNumber of Signal Positions64Number of Positions96Number of Rows6Number of Columns16	Shroud Style	Partially Shrouded
Number of Pairs32StackableNoNumber of Signal Positions64Number of Positions96Number of Rows6Number of Columns16	Configuration Features	
StackableNoNumber of Signal Positions64Number of Positions96Number of Rows6Number of Columns16	Number of Ground Positions	32
Number of Signal Positions64Number of Positions96Number of Rows6Number of Columns16	Number of Pairs	32
Number of Positions96Number of Rows6Number of Columns16	Stackable	No
Number of Rows6Number of Columns16	Number of Signal Positions	64
Number of Columns 16	Number of Positions	96
	Number of Rows	6
PCB Mount Orientation Vertical	Number of Columns	16
	PCB Mount Orientation	Vertical



Per a contact Characteristics  Portact Type Contact Underplating Material Thickness Contact Mating Area Plating Material Finish Contact Shape & Form Contact Underplating Material Contact Shape & Form Contact Contact Termination Area Plating Material Finish Contact Type Contact Mating Area Plating Material Contact Current Rating Material Contact Current Rating (Max) Contact Current Rating (	
gnal Characteristics  Number of Differential Pairs per Column  2 Data Rate 25 Gb/s  Primary Product Color Black  Contact Features  Contact Mating Area Length Contact Layout Inline  Contact Type Pin  Contact Underplating Material Thickness Contact Mating Area Plating Material Thickness Contact Mating Area Plating Material Thickness Contact Underplating Material Thickness Contact Mating Area Plating Material Thickness Contact Mating Area Plating Material Thickness Contact Mating Area Plating Material Contact Shape & Form Contact Shape & Form Contact Underplating Material Contact Underplating Material Contact Current Rating (Max)  Contact Base Material Contact Current Rating (Max)  Permination Features	
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Contact Current Rating (Max) .75 A  ermination Features	
ermination Features	ЭУ
Termination Post & Tail Length 1.4 mm[.05	
	ō in]
Termination Method to PCB Through H	ole - Press-Fit
echanical Attachment	
PCB Mount Alignment Type Locating Po	
Guide Hardware With	osts
Mating Retention Without	osts
PCB Mount Retention With	osts
PCB Mount Retention Type Action/Cor	osts
Mating Alignment With	npliant Tail & Screw



Mating Alignment Type	Guide Pin
Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	2
End Wall Location	Open
Housing Material	LCP (Liquid Crystal Polymer)
Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
Connector Length	36.9 mm[1.453 in]
Connector Height	11.95 mm[.47 in]
Connector Width	12.7 mm[.5 in]
	.039 in
PCB Hole Diameter	.39 mm[.015 in]
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Compatible With Approved Standards Products	UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tube, Package

## **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241)



Does no	t contain	RFACH	SVHC
D062 110	t Contain	NL A C H	$\mathcal{I}$

Free	h -	Low Halogen - Br, Cl, F, I < 900 ppm per nomogenous material. Also BFR/CFR/PVC
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### Solder Process Capability

Not applicable for solder process capability

#### Product Compliance Disclaimer

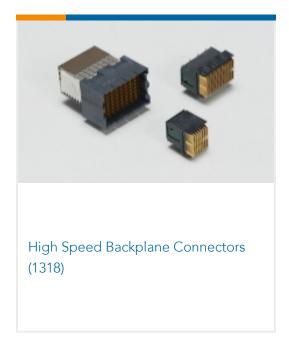
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**





## Also in the Series | IMPACT



## Customers Also Bought





















### **Documents**

**Product Drawings** 

IMP100S,H,V2P16C,LG,OEW39,4.5

English

**CAD Files** 

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_2057737-1\_A\_c-2057737-1-a.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2057737-1\_A\_c-2057737-1-a.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2057737-1\_A\_c-2057737-1-a.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Datasheets & Catalog Pages

96 Position, Mating Alignment, Guide Pin Mating Alignment Type, 6 Row, 16 Column, PCB Mount Header, Vertical, IMPACT, High Speed Backplane Connectors



## 7-1773458-1\_IMPACT\_BACKPLANE\_CONNECTOR\_SYSTEM\_CATALOG

English

**Product Specifications** 

**Application Specification** 

English

Agency Approvals

Agency Approval Document

English